

ABSTRACT OF THE DISCLOSURE

A method for manufacturing thermal heads comprises providing a substrate having a first surface, a second surface opposite the first surface, heaters disposed on the first surface, and pairs of electrodes disposed on the first surface, the electrodes of each pair of electrodes being disposed in spaced-apart, confronting relation to each other. A driver IC is mounted on each of the electrodes. The driver ICs are then encapsulated with a resin. Grooves are formed in at least one of the first surface and the second surface of the substrate so that the electrodes of each pair of electrodes are disposed symmetrically with respect to one of the grooves. The substrate is then cut along the grooves to form individual thermal heads each having a heater, at least one of the driver ICs for providing a drive signal to drive the heater, and a sealing element formed by the resin for protecting the driver IC.